

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIA-HUI LEE	07/27/2016
CHEN-WEI PAN	07/26/2016
YI-WEI CHIU	07/26/2016
TZU-CHAN WENG	07/27/2016
RECEIVING PARTY DATA	
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Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15223933
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NAME OF SUBMITTER:	SPENCER GARTH
SIGNATURE:	/spencer garth/
DATE SIGNED:	08/01/2016
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Chia-Hui LEE, Chen-Wei PAN, Yi-Wei CHIU, and Tzu-Chan WENG
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as
described and set forth in the below identified application for United States Letters Patent:

Title: STRUCTURE AND FORMATION METHOD OF SEMICONDUCTOR DEVICE
STRUCTURE

Filed: July 29, 2016 Serial No. 15/223,933
Executed on: July 26, 2016 and July 27, 2016

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2016.07.27 Chia Hui Lee
Date Name: Chia-Hui LEE (Last name: LEE)

2016.7.26 Chen Wei Pan.
Date Name: Chen-Wei PAN (Last name: PAN)

2016/7/26 Yi Wei Chiu
Date Name: Yi-Wei CHIU (Last name: CHIU)

2016 7/27 Tzu Chan Weng
Date Name: Tzu-Chan WENG (Last name: WENG)